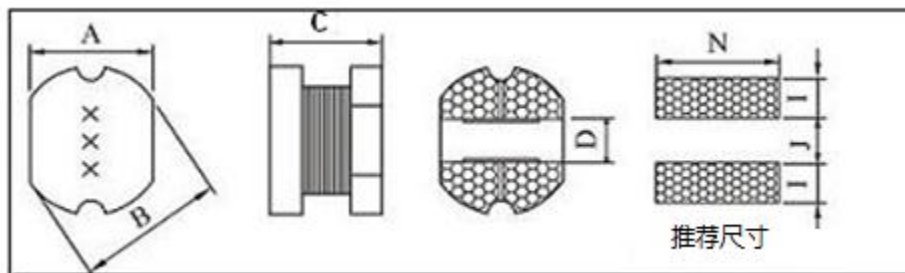


## 1、产品概要 / Outline

- ◆ 铁氧体结构、低直流电阻
- ◆ 高能量储存、高品质因素
- ◆ 电感值范围较大
- ◆ 优异的端面强度和良好的焊锡性
- ◆ 工作温度：-40°C ~ +125°C
- ◆ 主要应用于医疗仪器、数字功放、笔记本电脑、网络通讯、电子产品等



## 2、外观尺寸/ Appearance size 单位:mm



A±0.3	B±0.3	C±0.3	D	N	J	l
9.0	10.0	4.0	2.9	9.5	4.5	2.5

## 3、电气特性/Electrical characteristics

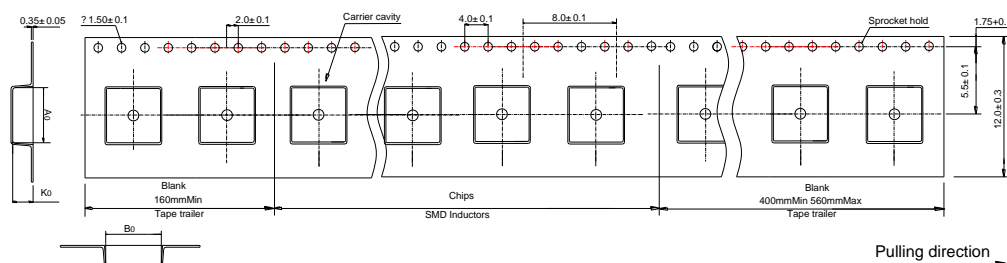
型号/NO	L/uH	DCR (Ω)	Isat(A)	Irms(A)
CD104-100K	10	0.03	5.50	6.0
CD104-120K	12	0.05	4.32	5.5
CD104-150K	15	0.06	4.00	5.1
CD104-180K	18	0.07	3.85	4.6
CD104-220K	22	0.08	3.75	4.2
CD104-270K	27	0.09	3.40	4.0
CD104-330K	33	0.10	3.00	3.5
CD104-390K	39	0.1	2.55	2.95
CD104-470K	47	0.15	2.20	2.8
CD104-560K	56	0.17	2.00	2.5
CD104-680K	68	0.18	1.84	2.3
CD104-820K	82	0.2	1.45	2.0
CD104-101K	100	0.25	1.00	1.7
CD104-121K	120	0.34	0.76	1.5
CD104-151K	150	0.40	0.55	1.2
CD104-181K	180	0.54	0.45	1.00
CD104-221K	220	0.62	0.40	0.95
CD104-271K	270	0.72	0.30	0.9
AP104-331K	330	0.95	0.25	0.85
CD104-391K	390	1.10	0.20	0.82

## 注释

- ◆ K 表示电感值的公差为±10%，M 表示电感值的公差为±20%
- ◆ K said inductance tolerance is ±10%, M said inductance tolerance is ± 20%
- ◆ 所有数据基于环境温度 25°C条件下测试
- ◆ All data is based on testing at an ambient temperature of 25 °C
- ◆ 测试条件：100KHz/0.25V
- ◆ 本页面未能录入全部或最新的数据，请您在订购前向本公司咨询精准参数及样品。
- ◆ We were unable to input all or the latest data on this page. Please consult our company for accurate parameters and samples before placing an order.

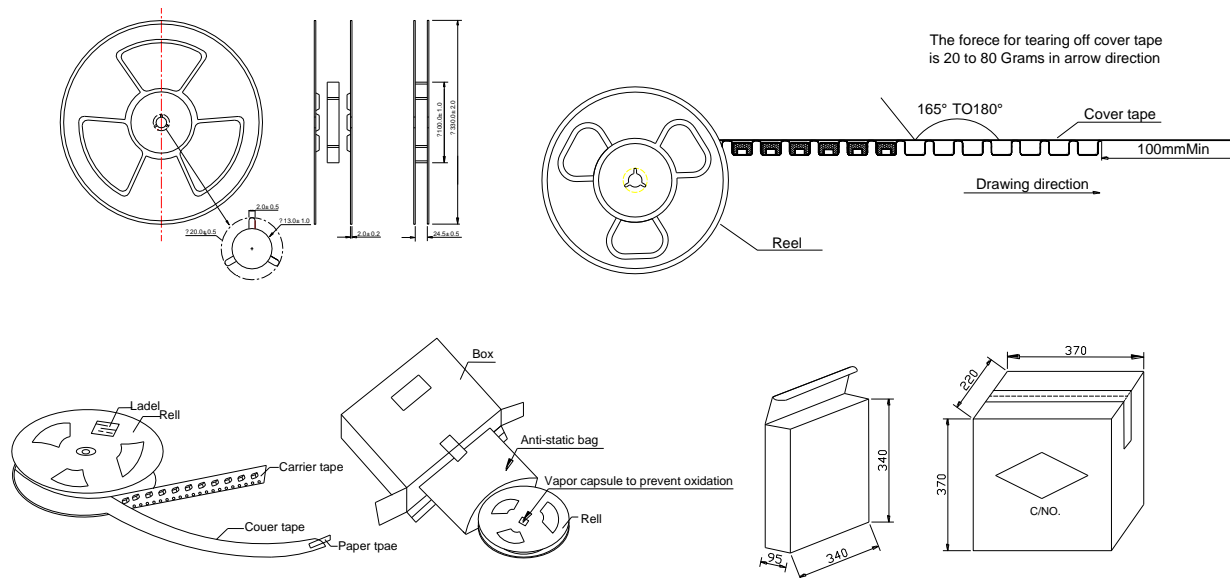
## 4 包装规格/ Packaging specifications 单位/mm

(1)、TAPE DIMENSIONS (unit: mm) & QUANTITIES (unit: PCS)



Type	Tape Dimensions			Reel	Quantities/Reel
	A <sub>0</sub>	B <sub>0</sub>	K <sub>0</sub>		
CD104	9.2	10.2	4.2	330*12	1000 PCS

(2)、DIMENSIONS OF REEL & TAPING FIGURES AND DRAWING DIRECTION



(3)、BOX AND CASE DIMENSIONS(UNIT:mm)&PACKAGING QUANTITIES(UNIT:PCS)

Type	Quantities(Unit:mm)	Quantities(Unit:m m)
	Inner Carton	Outer Carton
CD104	4/4000 PCS	4/16000PCS

5、焊接/welding

• 焊接原材料 Soldering Materials

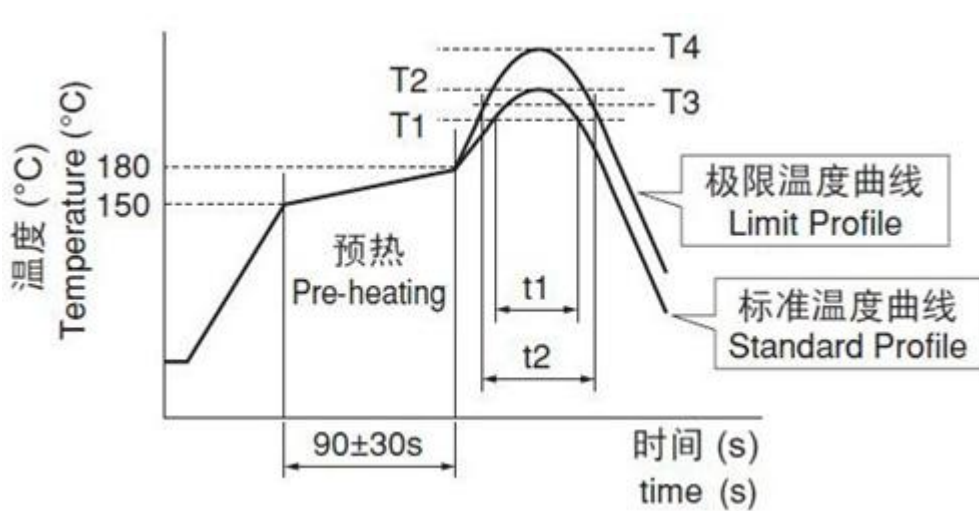
( a ) 焊料：推荐使用 96.5Sn/3.0Ag/0.5Cu 焊料，或者采用 Sn 含量不超过 97%的锡合金焊料。Solder: It is recommended to use 96.5Sn/3.0Ag/0.5Cu solder, or use Tin alloy solder with a Tin content not exceeding 97%.

( b ) 助焊剂：推荐使用松香类助焊剂，请勿使用强酸性助焊剂（含氯量超过 0.2wt % ），并且请勿使用水溶性助焊剂。Flux: It is recommended to use rosin-based flux. Acidic flux (with chlorine content exceeding 0.2wt %) and water-soluble flux are forbidden.

• 焊接温度及要求 Soldering Temperature & Requirements

( 1 ) 回流焊 Reflow Soldering

回流焊温度曲线 Reflow Soldering Temperature Profile

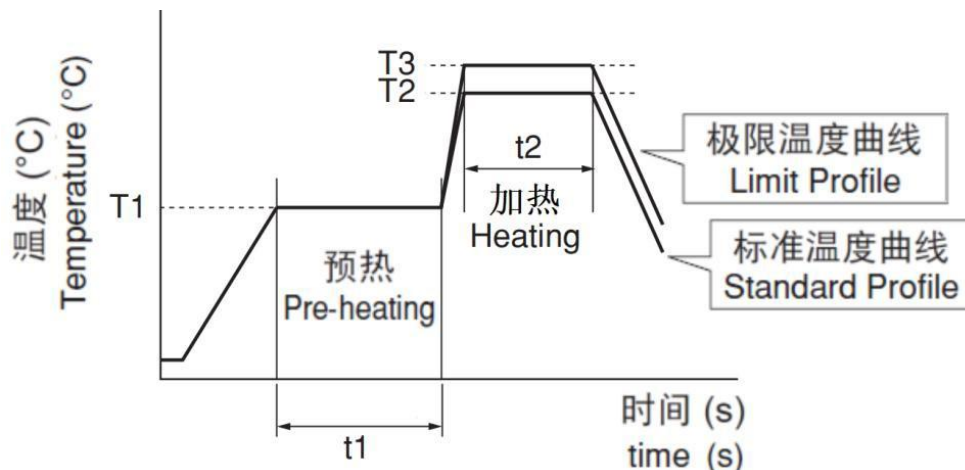


回流焊要求 Reflow Soldering Requirements

标准温度曲线Standard Profile				极限温度曲线Limit Profile			
加热Heating		峰值温度 Peak Temp. ( T2 )	回流焊 次Cycle Of Reflow	加热Heating		峰值温度 Peak Temp. ( T4 )	回流焊次数 Cycle Of Reflow
加热 Tem p. ( T1 )	时间 Ti me ( t1 )			温度 Temp. ( T3 )	时间 Time ( t2 )		
220°C	30~60s	245±3°C	≤2	230°C	≤60s	260°C/10s	1

(2)、波峰焊 Flow Soldering

波峰焊温度曲线 Flow Soldering Temperature Profile



波峰焊要求Flow Soldering Requirements

预热 Pre-heating		标准温度曲线 Standard Profile			极限温度曲线Limit Profile		
		加热Heating		波峰次数 Cycle Of Flow	加热		波峰次数 Cycle Of Flow
温度 Temp ( T1 )	时间 Time ( t1 )	温度 Temp ( t2 )	时间 Time ( t2 )		温度 Temp. ( T3 )	时间 Time ( t2 )	
150°C	≥60s	250°C	4s ~ 6s	≤2	265±3°C	≤5s	1

6、其他

- ◆ 本产品为无铅，请采用无铅环境作业
- ◆ Other: Our company's products are lead-free, please operate in a lead-free environment
- ◆ 由于页面限制，更多资料请联系我司
- ◆ Due to page limitations, please contact our company for more information
- ◆ 在过载电流等不正常条件下，本电感产品无自我保护功能。
- ◆ Under abnormal conditions such as overload current, this inductor product has no self-protection function.